



November, 2007

TO: Samtec Sales Associates

Samtec will begin changing the plating on the solder tails of the QSE, QTE, QSH, QTH, QTS, QSS, BSE, BTE, BSH, BTH, BSS, BTS, MIS, and MIT Series from Gold flash to Matte Tin. This plating change includes the tails on the signal pins for all series listed, and the tails on the ground plane on the Q-Series<sup>®</sup> and MIS/MIT products. Please note that the contact area on the signal pins and ground plane remain gold. We expect this change to take up to six months to complete.

Samtec historically designs surface mount interconnect systems with Gold on the contact area and Tin on the tails. Continuous process improvements in our electroplating capabilities now permit us to offer this same selective Gold/Tin plating combination on our Q-Series<sup>®</sup>, B-Series, and MIS/MIT products.

This plating change does not affect the call out/Samtec part number customers have been purchasing from us. For instance, if your customer purchases a QTE-040-01-L-D-A, they will continue to purchase that same callout, but they will receive Matte Tin plating on the solder tails. All Gold plating is still available as an ASP.

If you have any questions about this plating change please contact our Customer Engineering Support at +812-944-6733 or at [ces@samtec.com](mailto:ces@samtec.com).

Samtec, Inc.